Title of the Invention: Chemical Mechanical Abrasive Composition for Use in Semiconductor Processing

Abstract of the Disclosure

The invention provides a chemical-mechanical abrasive composition for use in semiconductor processing, which comprises 70-95% by weight of an aqueous medium, 1-25 % by weight of an abrasive, 0.1-20% by weight of an abrasion accelerator, wherein the abrasion accelerator comprises mono-carboxy group- or an amido group-containing compound and optionally a nitrate salt. The chemical-mechanical abrasive composition of the invention can further comprise an anionic surfactant, e.g. polycarboxylic acid or polyacrylic acid copolymer, so as to reduce the viscosity of the abrasive composition.